Low-Voltage CMOS Hex Buffer with Open Drain Outputs

With 5 V−Tolerant Inputs

MC74LCX07

The MC74LCX07 is a high performance hex buffer operating from a 1.65 to 5.5 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers. These LCX devices have open drain outputs which provide the ability to set output levels, or do active HIGH AND or active LOW OR functions. A V_I specification of 5.5 V allows MC74LCX07 inputs to be safely driven from 5.0 V devices.

Features

- Designed for 1.65 to 5.5 V V_{CC} Operation
- 5.0 V Tolerant Inputs/Outputs
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Output Sink Capability @ 3.0 V
- Near Zero Static Supply Current (10 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 100 mA
- Wired OR, Wired AND
- Output Level Can Be Set Externally Without Affecting Speed of Device
- ESD Performance: Human Body Model >2000 V
- These Devices are Pb Free, Halogen Free/BFR Free and are RoHS Compliant

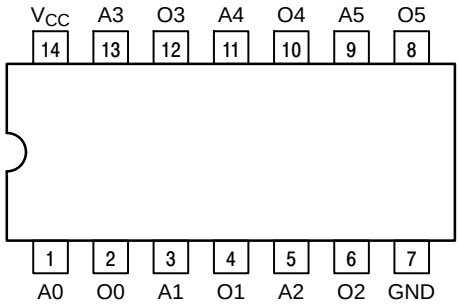
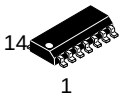
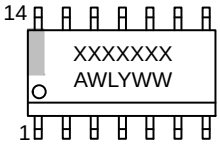


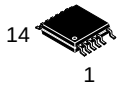
Figure 1. Pinout: 14−Lead (Top View)

MARKING DIAGRAMS



SOIC−14
D SUFFIX
CASE 751A





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CASE 948G

XXXX
XXXX

XXXXXX	= Specific Device Code
A	= Assembly Location
L, WL	= Wafer Lot
Y, YY	= Year
W, WW	= Work Week
G or ▪	= Pb−Free Package

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

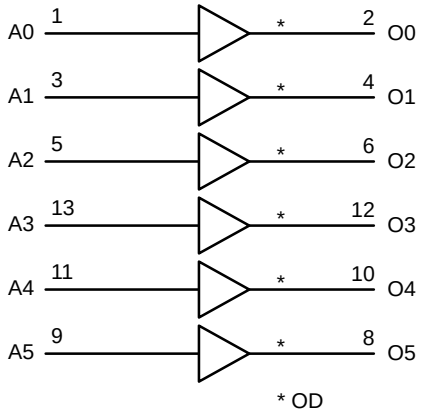


Figure 2. Logic Diagram

PIN NAMES

Pins	Function
An On	Data Inputs Outputs

TRUTH TABLE

An	On
L H	L Z

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V_{CC}	DC Supply Voltage		−0.5 to +6.5	V
V_I	DC Input Voltage (Note 1)		−0.5 to +6.5	V
V_O	DC Output Voltage (Note 1)	Active−Mode (High or Low State) Tri−State Mode Power−Down Mode (V_{CC} = 0 V)	−0.5 to V_{CC} + 0.5 −0.5 to +6.5 −0.5 to +6.5	V
I_{IK}	DC Input Diode Current	V_I < GND	−50	mA
I_{OK}	DC Output Diode Current	V_O < GND	−50	mA
I_O	DC Output Source/Sink Current		±50	mA
I_{CC} or I_{GND}	DC Supply Current per Supply Pin or Ground Pin		±100	mA
T_{STG}	Storage Temperature Range		−65 to +150	C
T_L	Lead Temperature, 1 mm from Case for 10 secs		260	C
T_J	Junction Temperature Under Bias			

RECOMMENDED OPERATING CONDITIONS

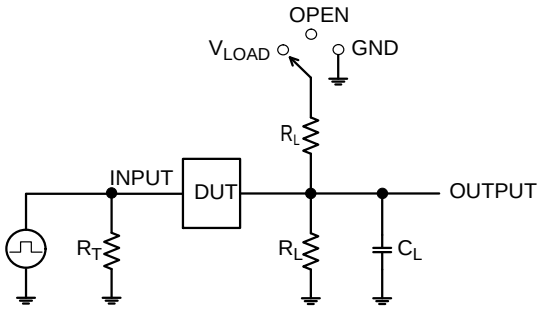
Symbol	Parameter		Min	Typ	Max	Unit
V_{CC}	Supply Voltage	Operating	1.65	3.3	5.5	V
		Data Retention Only	1.5	3.3	5.5	
V_I	Digital Input Voltage		0	–	5.5	V
V_O	Output Voltage	Active Mode (High or Low State)	0	–	V_{CC}	V
		Tri–State Mode	0	–	5.5	
		Power Down Mode (V_{CC} = 0 V)	0	–	5.5	
T_A	Operating Free–Air Temperature		–40	–	+125	C
t_r, t_f	Input Rise or Fall Rate	V_{CC} = 1.65 V to 1.95 V	0	–	20	nS/V
		V_{CC} = 2.3 V to 2.7 V	0	–	20	
		V_I from 0.8 V to 2.0 V, V_{CC} = 3.0 V	0	–	10	
		V_{CC} = 4.5 V to 5.5 V	0	–	5	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

4. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC ELECTRICAL CHARACTERISTICS

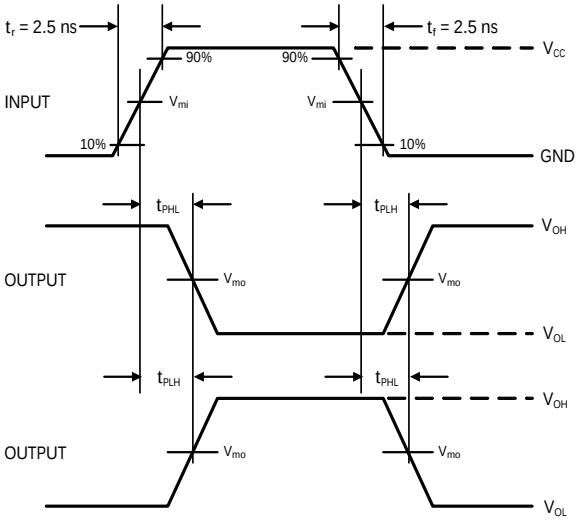
Symbol	Parameter	Conditions	V_{CC} (V)	T_A = −40°C to +85°C		T_A = −40°C to +125°C		Unit
				Min	Max	Min	Max	
V_{IH}	HIGH Level Input Voltage		1.65 – 1.95	0.65 x V_{CC}	–	0.65 x V_{CC}	–	V
			2.3 – 2.7	1.7	–	1.7	–	
			3.0 – 3.6	2.0	–	2.0	–	
			4.5 – 5.5	0.70 x V_{CC}	–	0.70 x V_{CC}	–	
V_{IL}	LOW Level Input Voltage		1.65 – 1.95	–	0.35 x V_{CC}	–	0.35 x V_{CC}	V
			2.3 – 2.7	–				

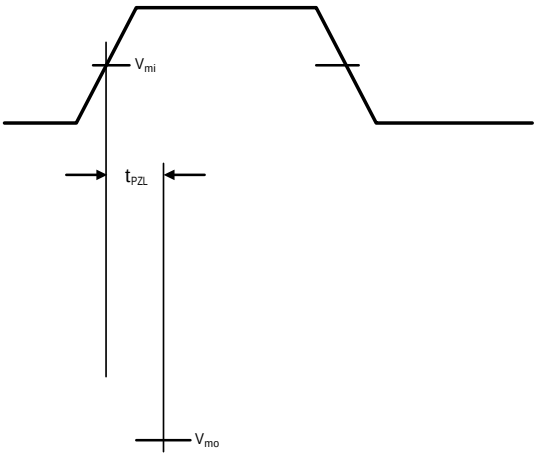


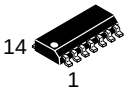
Test	Switch Position
t_{PLH} / t_{PHL}	Open
t_{PLZ} / t_{PZL}	V_{LOAD}
t_{PHZ} / t_{PZH}	GND

C_L includes probe and jig capacitance
R_T is Z_{OUT} of pulse generator (typically 50 Ω)
f = 1 MHz

Figure 3. Test Circuit







SCALE 1:1

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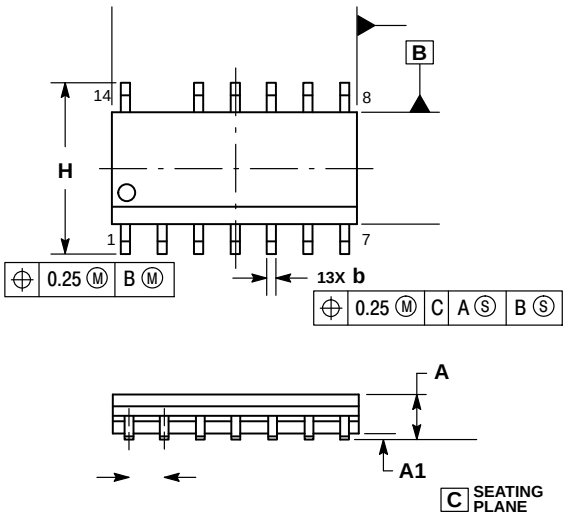
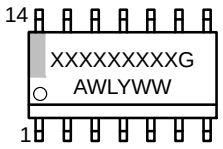


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

GENERIC
MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package

STYLES ON PAGE 2

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STYLE 7:
PIN 1. ANODE/CATHODE
2. COMMON ANODE
3. COMMON CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE